

T435T-600FP

4 A Snubberless™ Triac

Features

- High static and dynamic commutation
- Package is RoHS (2002/95/EC) compliant
- I_{GT} = 35 mA

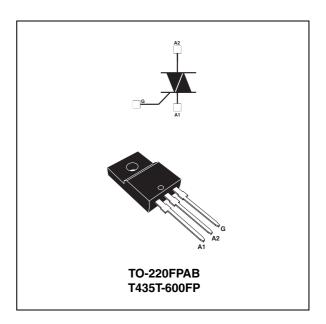
Applications

Specially designed for power tool applications, it can also be used to drive loads like motor speed controller, and kitchen equipment such as electro valves, light dimmers and similar.

Description

Available in through-hole package, the Triac T435T-600FP is suitable for general purpose AC switching.

Being a fully insulated package, the T435T-600FP provides insulation rated at 1500 V rms.



TM: Snubberless is a trademark of STMicroelectronics

Characteristics T435T-600FP

1 Characteristics

Table 1. Absolute maximum ratings (limiting values)

Symbol	Parameter	Value	Unit			
I _{T(RMS)}	On-state rms current (full sine wave) $T_c = 105 ^{\circ}\text{C}$		4	Α		
l	Non repetitive surge peak on-state current (full	F = 60 Hz	t = 16.7 ms	32	Α	
ITSM	cycle sine wave, T _J initial = 25 °C)	F = 50 Hz	t = 20 ms	30	A	
l ² t	I ² t Value for fusing	$t_p = 10 \text{ ms}$		6	A ² s	
dI/dt	Critical rate of rise of on-state current $I_G = 2 \times I_{GT}$, $t_r \le 100 \text{ ns}$	F = 120 Hz	T _j = 125 °C	50	A/μs	
V _{DSM} /V _{RSM}	Non repetitive surge peak off-state voiltage	epetitive surge peak off-state voiltage $t_p = 10 \text{ ms}$ $T_j = 25$		V _{DRM} /V _{RRM} + 100	V	
I _{GM}	Peak gate current $t_p = 20 \mu s$ T		T _j = 125 °C	4	Α	
P _{G(AV)}	Average gate power dissipation $T_j = 125 ^{\circ}\text{C}$			1	W	
T _{stg} T _j	Storage junction temperature range Operating junction temperature range			-40 to +150 -40 to +125	°C	

Table 2. Electrical characteristics, Snubberless (3 quadrants) $(T_i = 25 \, ^{\circ}C, \text{ unless otherwise specified})$

Symbol	Test conditions	Quadrant		Value	Unit
I _{GT} ⁽¹⁾	$V_D = 12 \text{ V R}_L = 30 \Omega$	I - II - III	MAX	35	mA
V _{GT}	$V_D = 12 \text{ V R}_L = 30 \Omega$	I - II - III	MAX	1.3	V
V_{GD}	$V_D = V_{DRM} R_L = 3.3 \text{ k}\Omega$	I - II - III	MIN	0.2	V
I _H ⁽²⁾	I _T = 100 mA		MAX	35	mA
IL	I _G = 1.2 x I _{GT}	1 - 111	MAX	50	mΛ
		II	MAX	80	mA
dV/dt (2)	$V_D = 67\% \ V_{DRM}$, gate open, $T_j = 125 \ ^{\circ}C$		MIN	750	V/µs
(dl/dt)c (2)	Without snubber, T _j = 125 °C		MIN	5.3	A/ms

^{1.} Minimum $\rm I_{GT}$ is guaranteed at 5% of $\rm I_{GT}$ max.

Table 3. Static electrical characteristics

Symbol	Test conditions			Value	Unit
V _{TM} ⁽¹⁾	$I_{TM} = 5.7 \text{ A, } t_p = 380 \mu\text{s}$	T _j = 25 °C	MAX	1.6	V
V _{TO} ⁽¹⁾	Threshold voltage	T _j = 125 °C	MAX	0.9	V
R _D ⁽¹⁾	Dynamic resistance	T _j = 125 °C	MAX	100	mΩ
I _{DRM} I _{RRM}	$V_{DRM} = V_{RRM}$	T _j = 25 °C	MAX	5	μΑ
		T _j = 125 °C		1	mA

^{1.} For both polarities of A2 pin referenced to A1 pin

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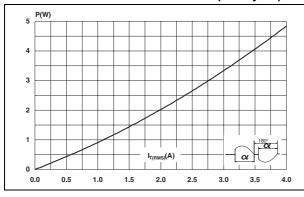
^{2.} For both polarities of A2 pin referenced to A1 pin

T435T-600FP Characteristics

Table 4. Thermal resistances

Symbol	Parameter	Value	Unit
R _{th(j-c)}	Junction to case (ac)	4.3	°C/W
R _{th(j-a)}	Junction to ambient	60	C/ VV

Figure 1. Maximum power dissipation versus Figure 2. On-state current (rms) versus case rms on-state current (full cycle) temperature (full cycle)



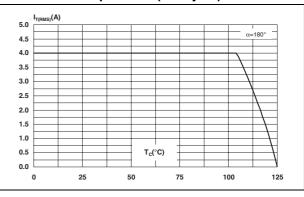
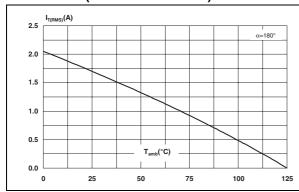


Figure 3. On-state current (rms) versus ambient temperature (free air convection)

Figure 4. Relative variation of thermal impedance versus pulse duration



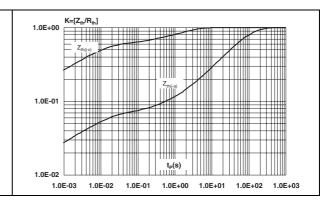
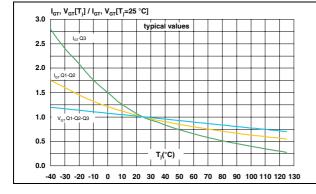
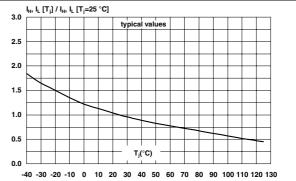


Figure 5. Relative variation of gate trigger current, and gate trigger voltage versus junction temperature

Figure 6. Relative variation of holding current and latching current versus junction temperature





Characteristics T435T-600FP

Figure 7. Surge peak on-state current versus Figure 8. Non-repetitive surge peak on-state number of cycles current for a sinusoidal

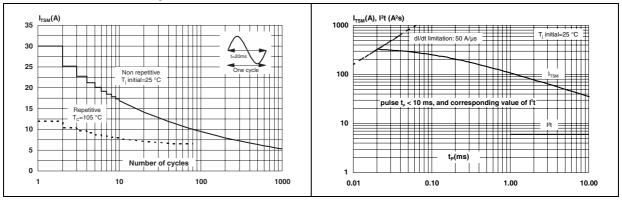


Figure 9. On-state characteristics (maximum values)

Figure 10. Relative variation of critical rate of decrease of main current (di/dt)c versus junction temperature

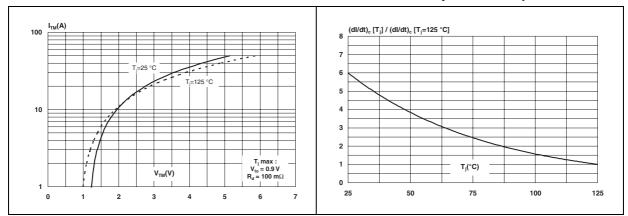
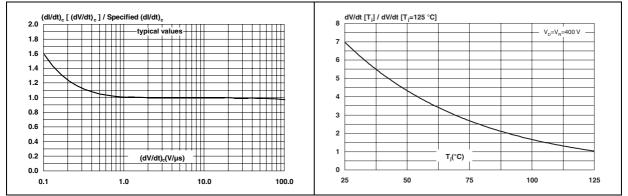


Figure 11. Relative variation of critical rate of decrease of main current (di/dt)c versus reapplied (dV/dt)c

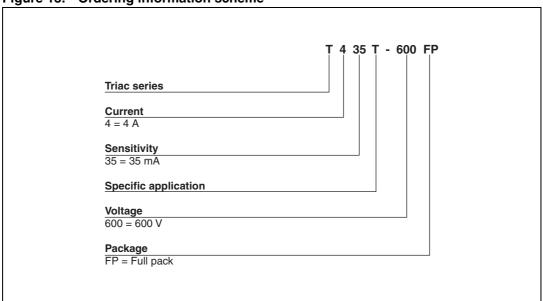
Figure 12. Relative variation of static dV/dt immunity versus junction temperature



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2 Ordering information scheme

Figure 13. Ordering information scheme

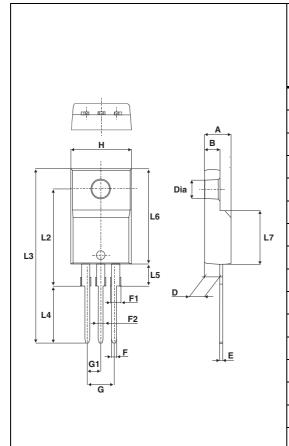


3 Package information

- Epoxy meets UL94, V0
- Lead-free packages

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Table 5. TO-220FPAB dimensions



	Dimensions				
Ref.	Millim	Millimeters		hes	
	Min.	Max.	Min.	Max.	
Α	4.4	4.6	0.173	0.181	
В	2.5	2.7	0.098	0.106	
D	2.5	2.75	0.098	0.108	
Е	0.45	0.70	0.018	0.027	
F	0.75	1	0.030	0.039	
F1	1.15	1.70	0.045	0.067	
F2	1.15	1.70	0.045	0.067	
G	4.95	5.20	0.195	0.205	
G1	2.4	2.7	0.094	0.106	
Ι	10	10.4	0.393 0.409		
L2	16	Тур.	0.63 Typ.		
L3	28.6	30.6	1.126 1.205		
L4	9.8	10.6	0.386 0.417		
L5	2.9	3.6	0.114 0.142		
L6	15.9	16.4	0.626	0.646	
L7	9.00	9.30	0.354	0.366	
Dia.	3.00	3.20	0.118 0.126		

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4 Ordering information

Table 6. Ordering information

Order code Marking		Package	Weight	Base qty	Packing mode
T435T-600FP	T435T-600	TO-220FPAB	2.0 g	50	Tube

5 Revision history

Table 7. Document revision history

Date	Revision	Changes	
09-Nov-2007	1	Initial release.	
14-Jun-2010	2	Updated ECOPACK statement.	

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